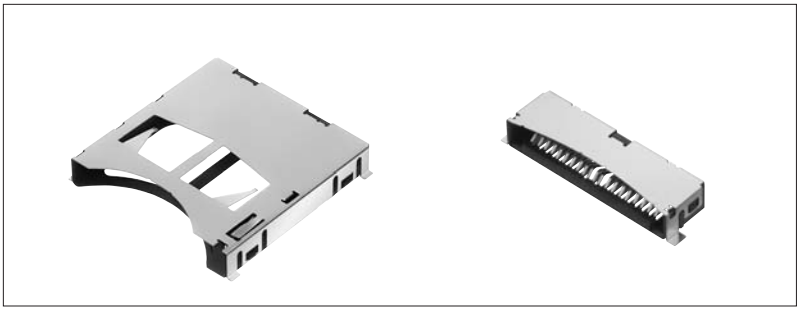
Connector for W-SIM

SCZA Series

RoHS compliant

High reliability contact structure best fit for portable devices.



Features

- Improved operability from long ejection stroke (5mm) and clear click feel.
- Good operational feel.
- Double contact-point for power and ground reduces risk of temporary power failure.
- Compact and low-profile suitable for portable devices.

Applications

- For mobile phones, PCs, and personal digital assistants

Typical Specifications

Items		Specifications
Structure	Applicable media	W-SIM
	Mounting type	Surface mounting type
	Mounting style	Standard mount
	Media ejection structure	Push-push type, Manual insertion/removal
Performance	Operating temperature range	−20℃ to +60℃
	Voltage proof	500V AC 1minute
	Insulation resistance (Initial)	1,000MΩ min.
	Contact resistance (Initial)	100mΩ max.
	Insertion and removal cycle	10,000cycles

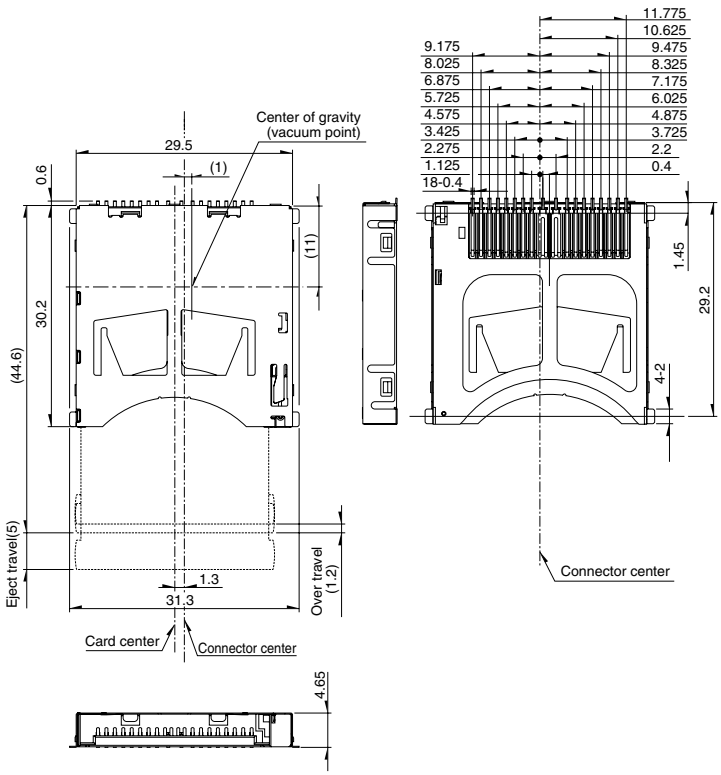
Product Line

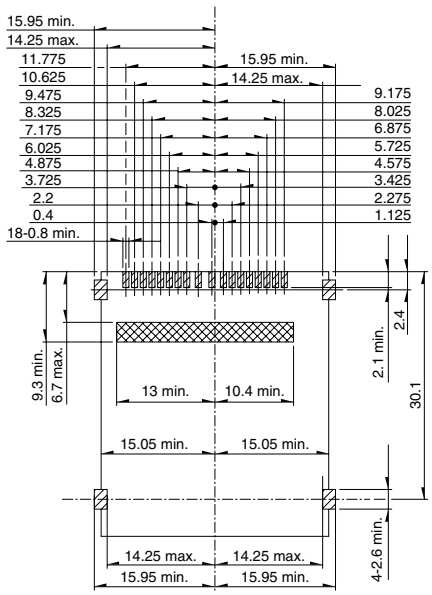
Media ejection structure	Mounting system	Features	Stand-off (mm)	Packing system	Product No.	Drawing No.
Push-push type	Standard mount	Without boss L type	0	Tray	SCZA1A0100	1
		With boss L type			SCZA1A0200	2
		Without boss 0.6mm type			SCZA1A0300	3
		With boss 0.6mm type			SCZA1A0400	4
		Without boss 1.2mm type			SCZA1A0500	5
		With boss 1.2mm type			SCZA1A0600	6
Manual insertion/removal		With boss L type			SCZA2A0100	7
		Without boss 0.6mm type			SCZA2A0200	8

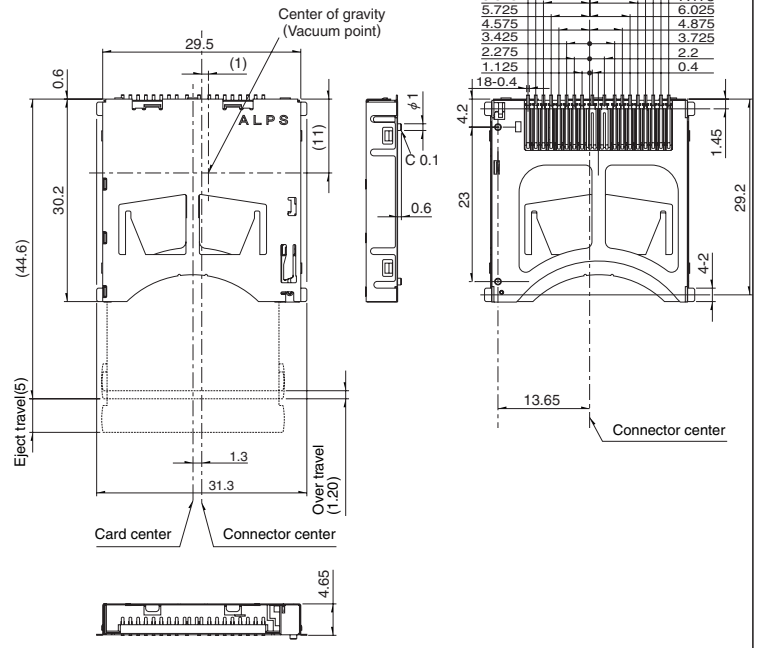
Dimensions

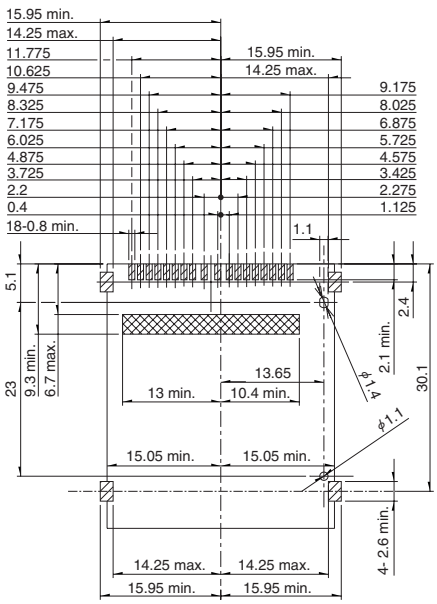
Unit:mm

No.	Style	PC board mounting hole dimensions (Viewed from the mounting face side)
1	**Push-push type** **Without boss L type**	
2	**Push-push type** **With boss L type**	





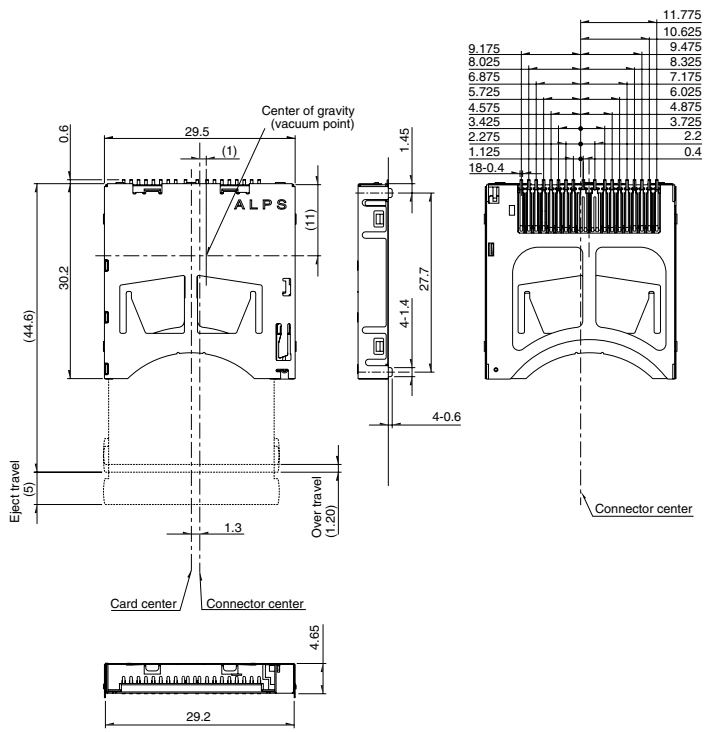


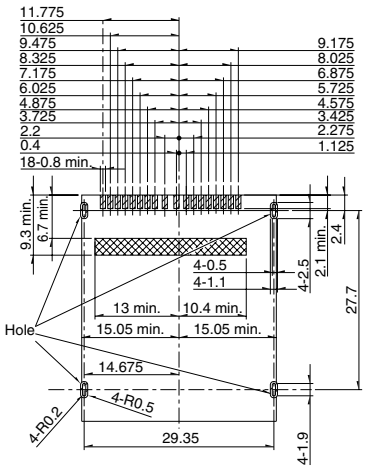


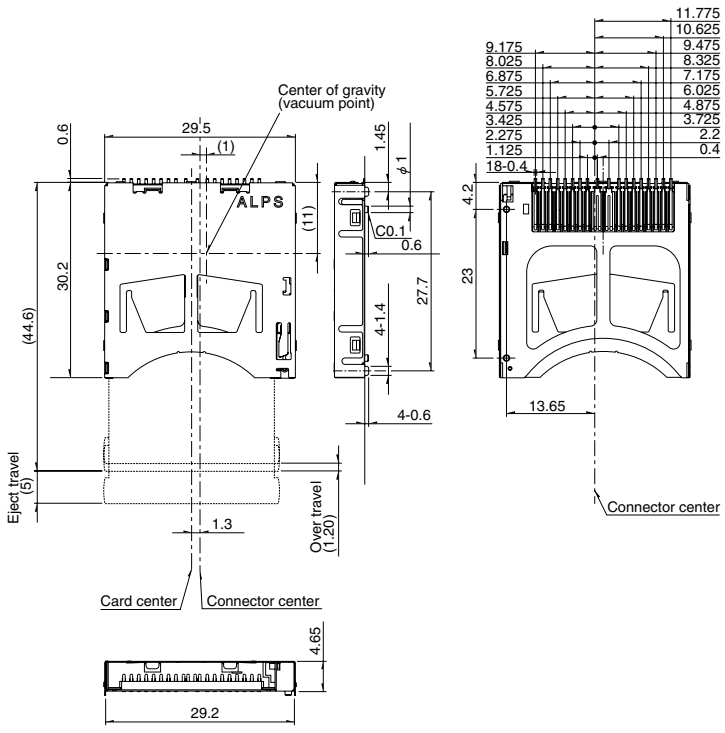
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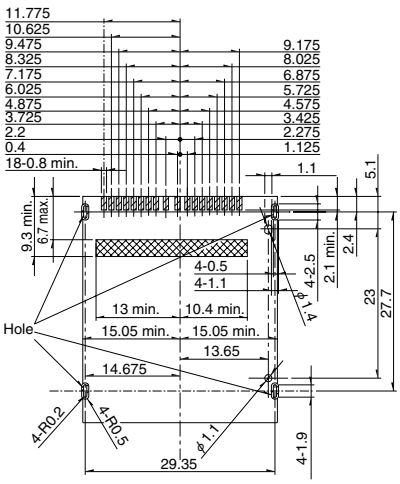
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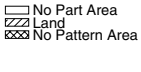
No.	Style	PC board mounting hole dimensions (Viewed from the mounting face side)
3	**Push-push type** **Without boss 0.6mm type**	
4	**Push-push type** **With boss 0.6mm type**	





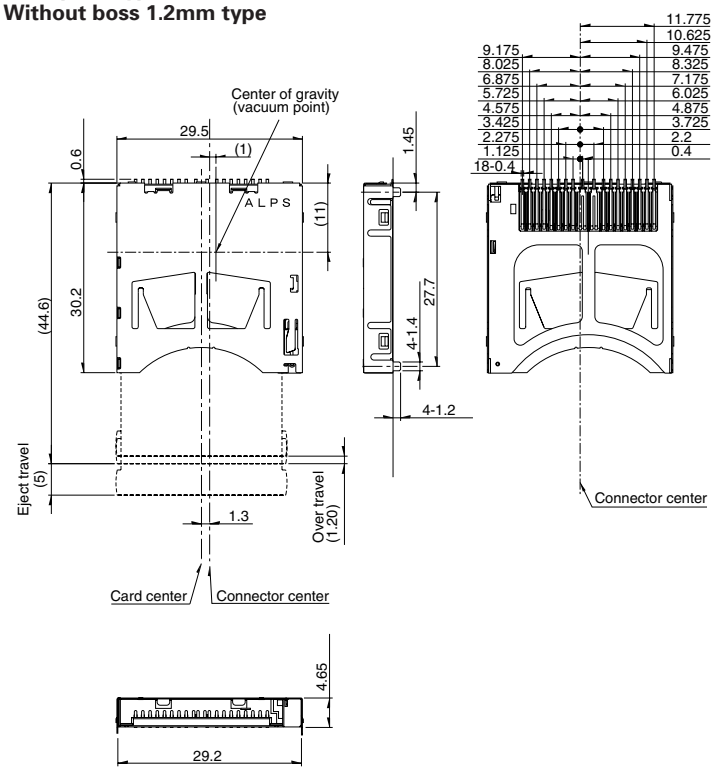
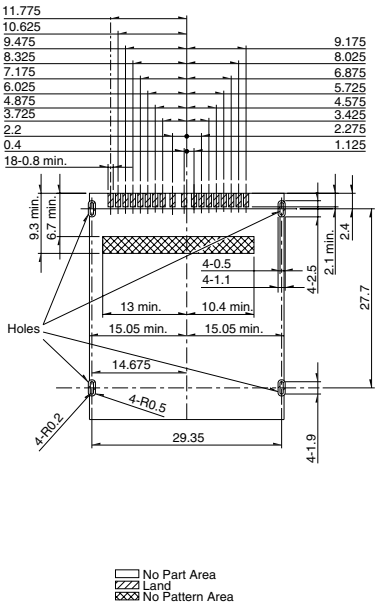
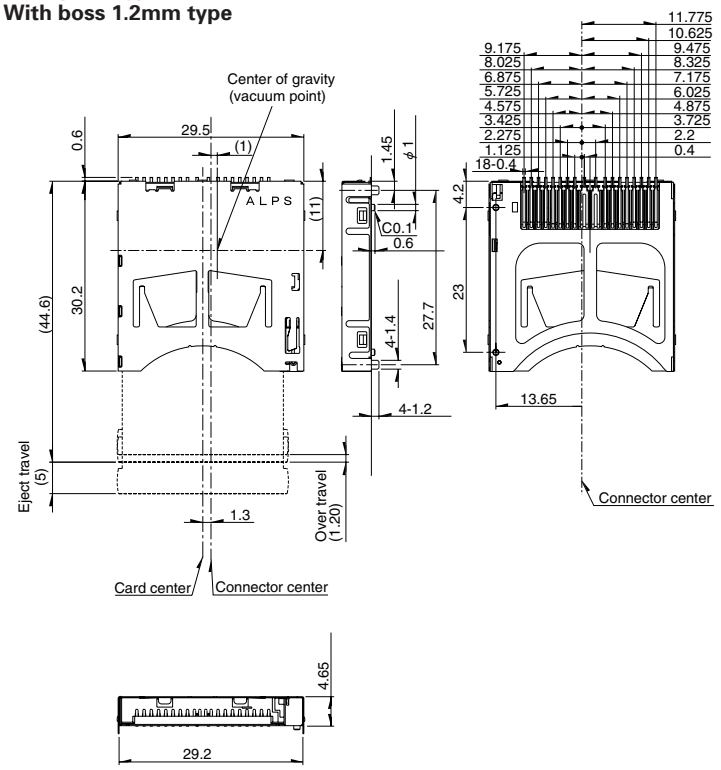
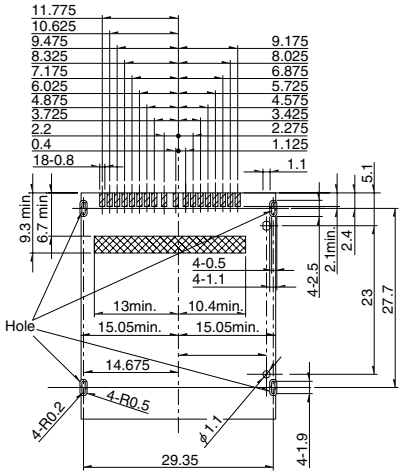






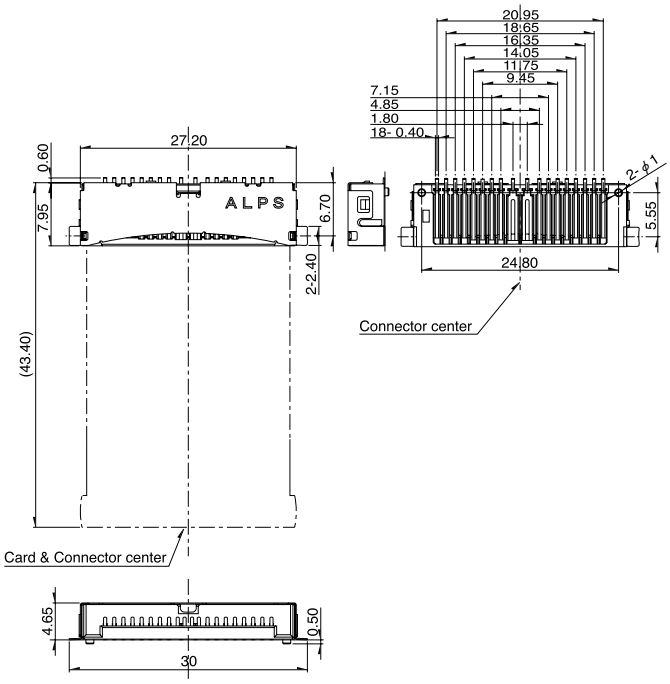
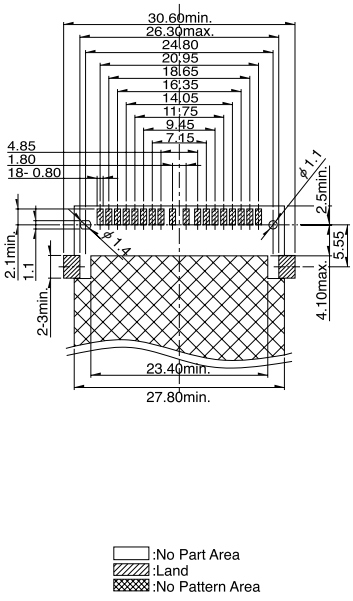
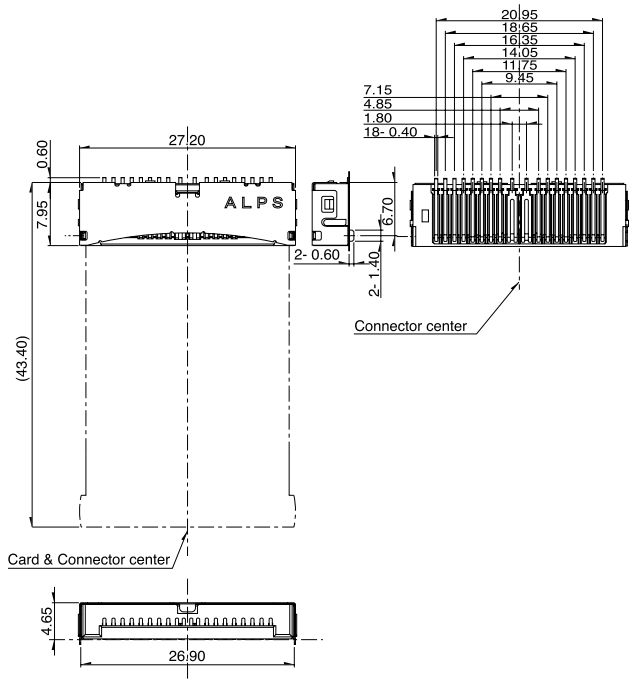
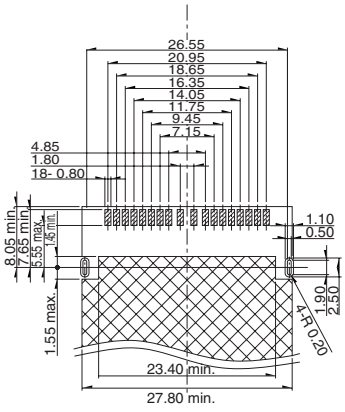
Dimensions

Unit:mm

No.	Style	PC board mounting hole dimensions (Viewed from the mounting face side)
5	**Push-push type** **Without boss 1.2mm type** 	
6	**Push-push type** **With boss 1.2mm type** 	

Dimensions

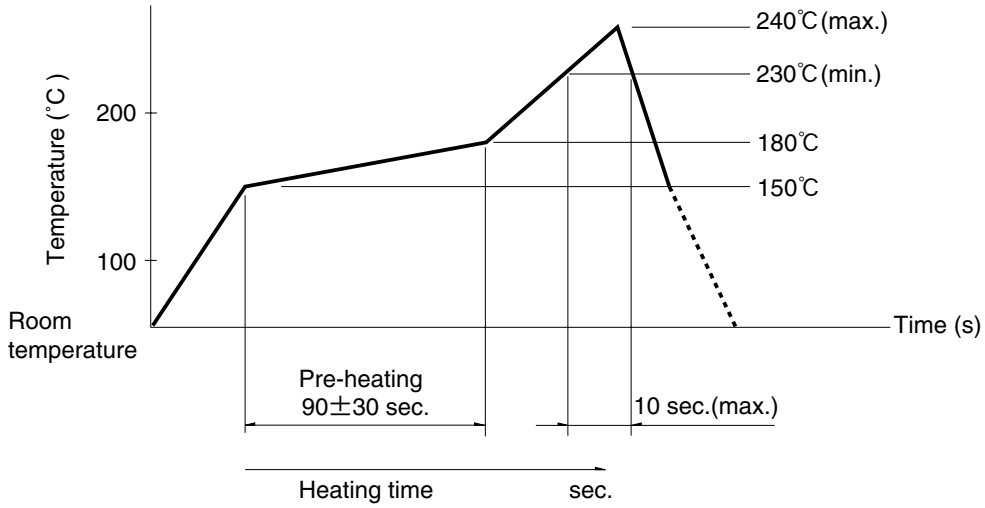
Unit:mm

No.	Style	PC board mounting hole dimensions (Viewed from the mounting face side)
7	**Manual insertion/removal** **With boss L type** 	
8	**Manual insertion/removal** **Without boss 0.6mm type** 	

Soldering Conditions

Example of Reflow Soldering Condition (Reference)

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T).
3. Temperature profile (Surface of products).



Cautions for using this product

1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
2. Avoid use of water-soluble soldering flux, since it may corrode the product.
3. Check and conform to reflow soldering requirements under actual mass production conditions.
4. PC board warping may alter the characteristics. Please take this into consideration when designing patterns and layout.
5. The card specifications are provided by the above manufactures. Products by other manufactures may not be compliant with these specifications and are subject to change without prior notice.